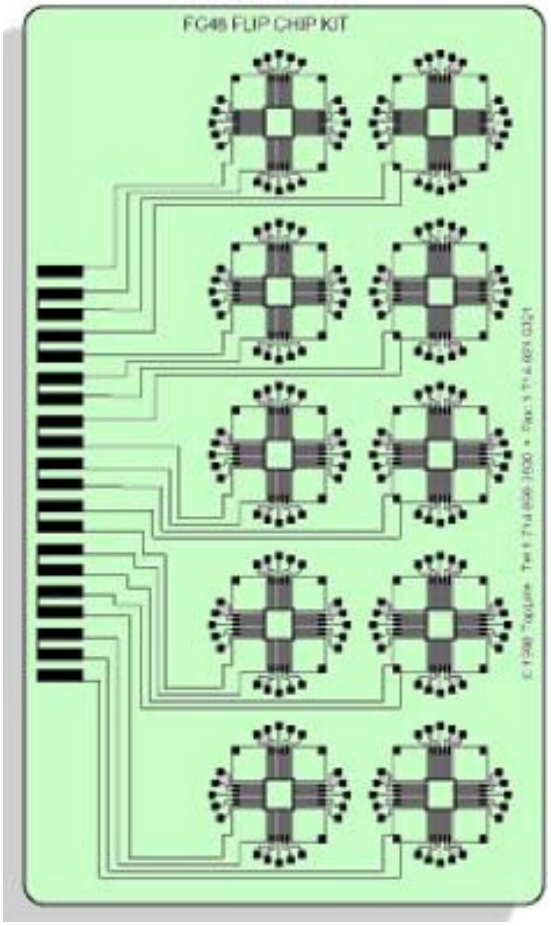
Flip Chip Kits



FC48
Flip Chip Kit

Board Features

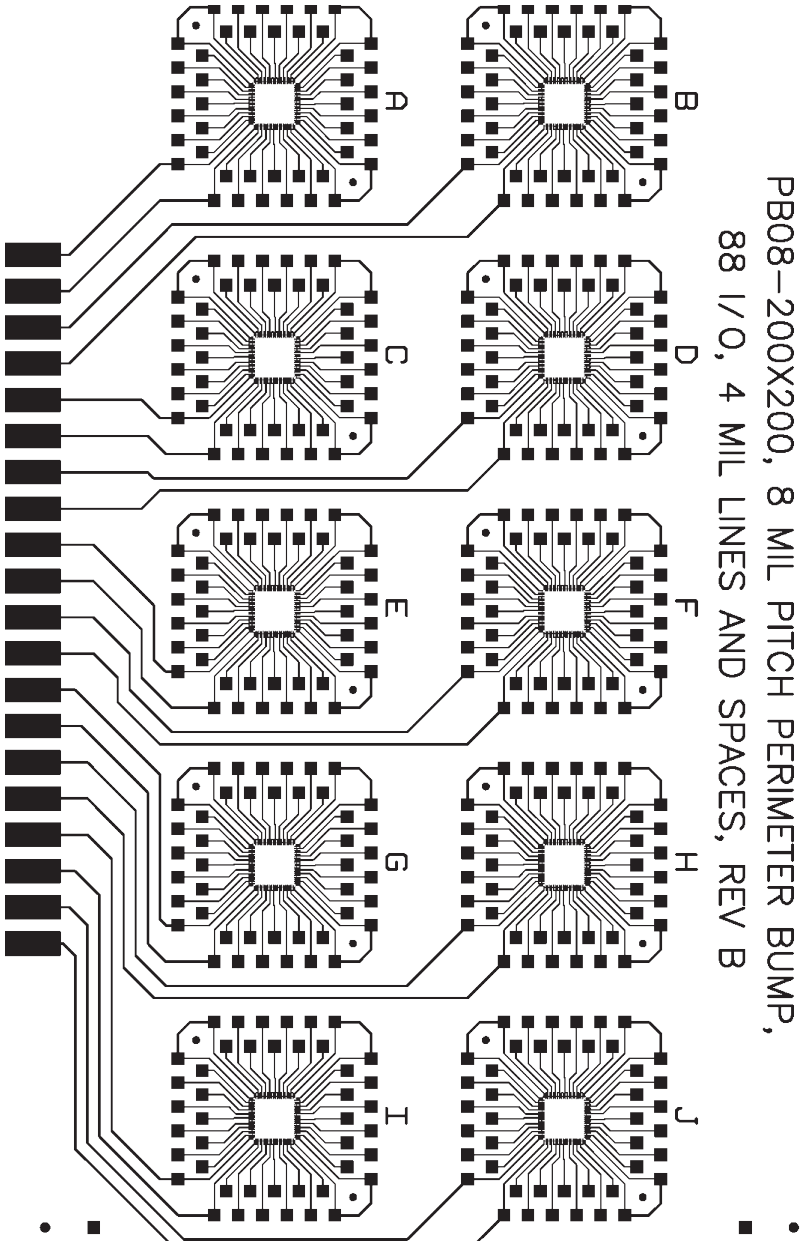
- White ceramic
- Tin composite screened ink
- No fiducial marks
- Traces 8 mil lines and spaces
- Fingers .156 (4.0mm) pitch
- Board 3.5" x 5x5" (89mm x 140mm)
- Board Thickness .035" (0.89mm)



FC88
Flip Chip Kit

Board Features

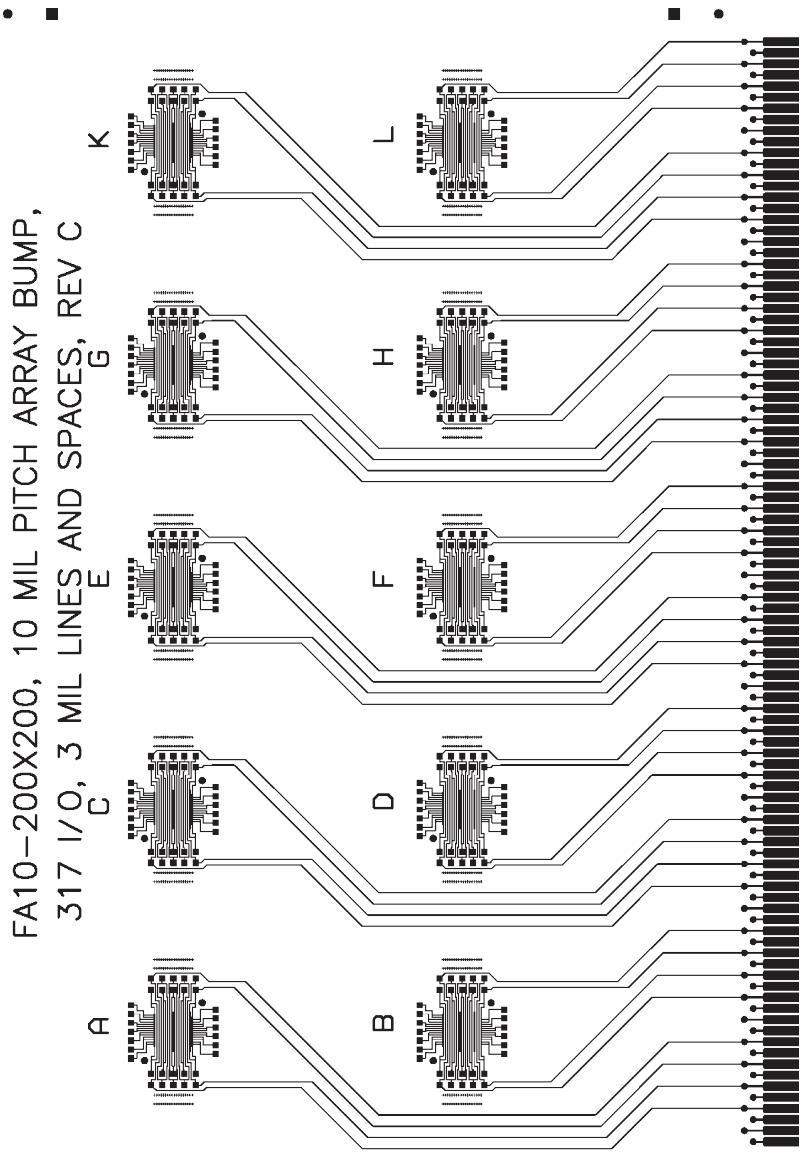
- Tetra-functional double sided FR-4
- 3-8 micro-inch ENIG immersion Gold over electroless nickel
- Local and Global Fiducial Marks
- Traces 4 mil lines and spaces
- Top side mounting FC88
- Bottom Side mounting FC220
- Green LPI Solder Mask
- Fingers .150" (3.83mm) pitch
- Board 3.5" x 5.5" (89mm x 140mm)
- Board Thickness .031" (0.8mm)
- 4-tooling holes .125" (3.17mm)



FC317
Flip Chip Kit

Board Features

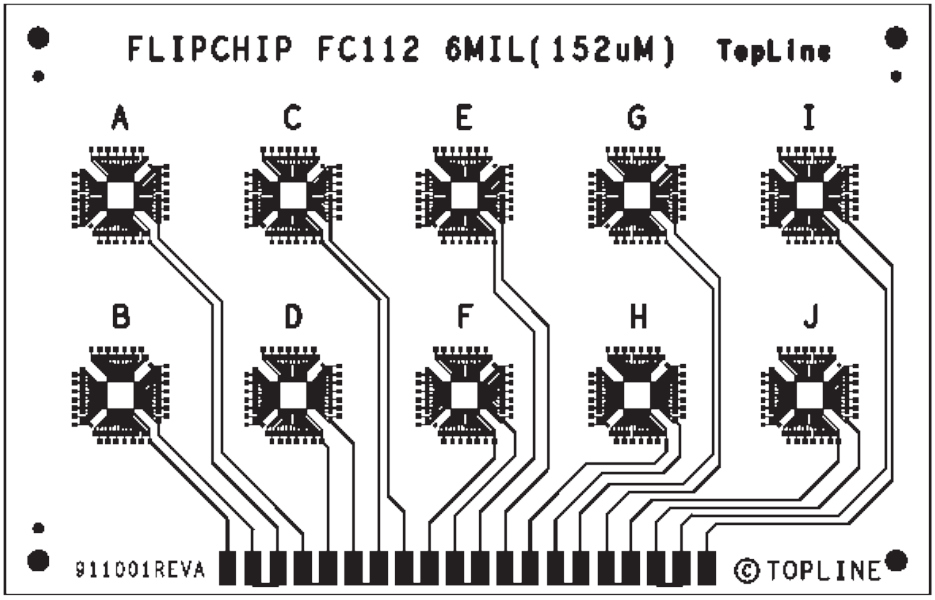
- 4-Layer FR-4
- Tg = 180 °C
- 3-8 micro-inch immersion Gold over electroless nickel
- 1/4-oz copper, plated up to 1-oz
- Local and global fiducial marks
- Traces 3 mil lines and spaces
- Single sided mounting 10-sites
- Green LPI solder mask
- Fingers .05" (1.27mm) pitch
- Board 3.8" x 5.5" (96mm x 140mm)
- Board Thickness .031" (0.8mm)
- 4-tooling holes .125" (3.17mm)



FC112
Flip Chip Kit

Board Features

- Tg 175 °C
- LPI soldermask
- Bondable Gold pads
- Fiducial marks
- Daisy chain test points
- 3.5" x 5.5" (89 x 140mm)
- Thickness .062" (1.5mm)



Other variations available upon request

- FC176 Flip Chip Substrate 901001
- FC220 Flip Chip Substrate 904001
- FC96 Flip Chip Ceramic Substrate 906001
- FC96 Flip Substate 907001